

Abstract of the Disclosure

A voltage is applied to an electrode of an electrostatic chuck for chucking a semiconductor substrate, and the application voltage
5 is controlled stepwise by means of a voltage control section. In the electrostatic chucking system, a temperature sensor may be provided for detecting the temperature of the semiconductor substrate held by the electrostatic chuck, wherein a signal output from the temperature sensor is input to the voltage control section to thereby
10 control the applied voltage.